

PROCESS FOR ISOTROPIC ETCHING OF COPPER
OR ALLOY AND STRUCTURES

5

ABSTRACT

Copper and copper alloys are etched to provide uniform and smooth surface by
employing an aqueous composition that comprises an oxidant, a mixture of at least one weak
complexant and at least one strong complexant for the copper or copper alloy, and water and has
10 a pH of about 6 to about 12 so as to form an oxidized etch controlling layer and to uniformly
remove the copper or copper alloy; and then removing the oxidized etch controlling layer with a
non-oxidizing composition. Copper and copper alloy structure, having smooth upper surfaces
are also provided.